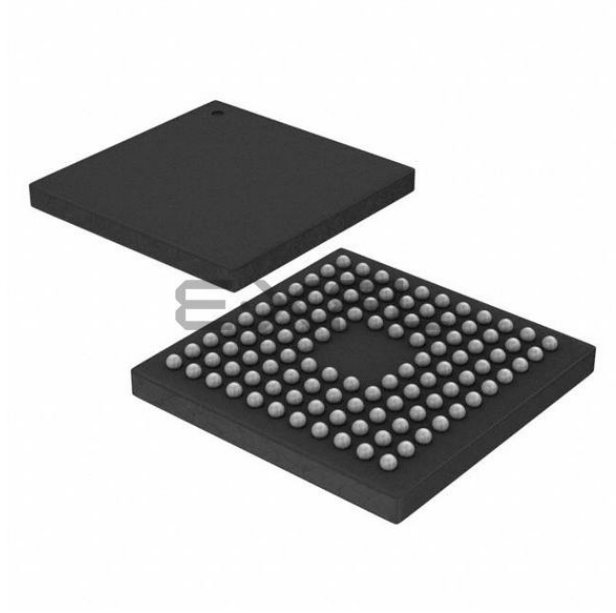

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I²C, IrDA, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	87
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LFBGA
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg990f64-bga112t

3. System Summary

3.1 System Introduction

The EFM32 MCUs are the world's most energy friendly microcontrollers. With a unique combination of the powerful 32-bit ARM Cortex-M3, innovative low energy techniques, short wake-up time from energy saving modes, and a wide selection of peripherals, the EFM32LG microcontroller is well suited for any battery operated application as well as other systems requiring high performance and low-energy consumption. This section gives a short introduction to each of the modules in general terms and also shows a summary of the configuration for the EFM32LG devices. For a complete feature set and in-depth information on the modules, the reader is referred to the EFM32LG Reference Manual.

A block diagram of the EFM32LG is shown in the following figure.

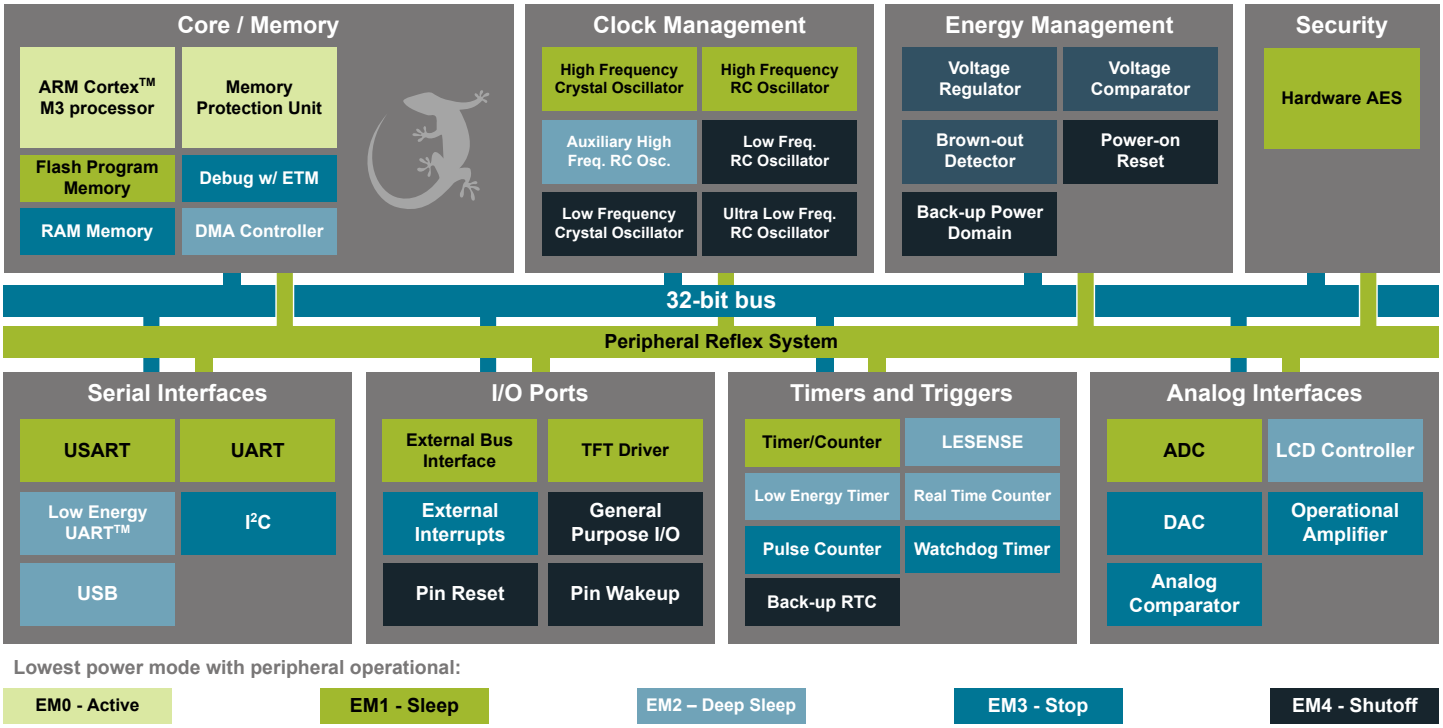

Figure 3.1. Block Diagram

3.1.1 ARM Cortex-M3 Core

The ARM Cortex-M3 includes a 32-bit RISC processor which can achieve as much as 1.25 Dhrystone MIPS/MHz. A Memory Protection Unit with support for up to 8 memory segments is included, as well as a Wake-up Interrupt Controller handling interrupts triggered while the CPU is asleep. The EFM32 implementation of the Cortex-M3 is described in detail in EFM32LG Reference Manual.

3.1.2 Debug Interface (DBG)

This device includes hardware debug support through a 2-pin serial-wire debug interface and an Embedded Trace Module (ETM) for data/instruction tracing . In addition there is also a 1-wire Serial Wire Viewer pin which can be used to output profiling information, data trace and software-generated messages.

3.1.3 Memory System Controller (MSC)

The Memory System Controller (MSC) is the program memory unit of the EFM32LG microcontroller. The flash memory is readable and writable from both the Cortex-M3 and DMA. The flash memory is divided into two blocks; the main block and the information block. Program code is normally written to the main block. Additionally, the information block is available for special user data and flash lock bits. There is also a read-only page in the information block containing system and device calibration data. Read and write operations are supported in the energy modes EM0 and EM1.

Module	Configuration	Pin Connections
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	93 pins	Available pins are shown in 5.11.3 GPIO Pinout Overview

Module	Configuration	Pin Connections
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	52 pins	Available pins are shown in 5.18.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[17:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
EM1 current (Production test condition = 14 MHz)	I_{EM1}	48 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	63	75	µA/MHz
		48 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	65	76	µA/MHz
		28 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	64	75	µA/MHz
		28 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	65	77	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	65	76	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	66	78	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	67	79	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	68	82	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	68	81	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	70	83	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	74	87	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	76	89	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	106	120	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	112	129	µA/MHz
EM2 current	I_{EM2}	EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.95[1]	1.7[1]	µA
		EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=85°C	—	3.0[1]	4.0[1]	µA
EM3 current	I_{EM3}	V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.65	1.3	µA
		V_{DD}= 3.0 V, T_{AMB}=85°C	—	2.65	4.0	µA
EM4 current	I_{EM4}	V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.020	0.055	µA
		V_{DD}= 3.0 V, T_{AMB}=85°C	—	0.44	0.90	µA

Note:
1. Using backup RTC.

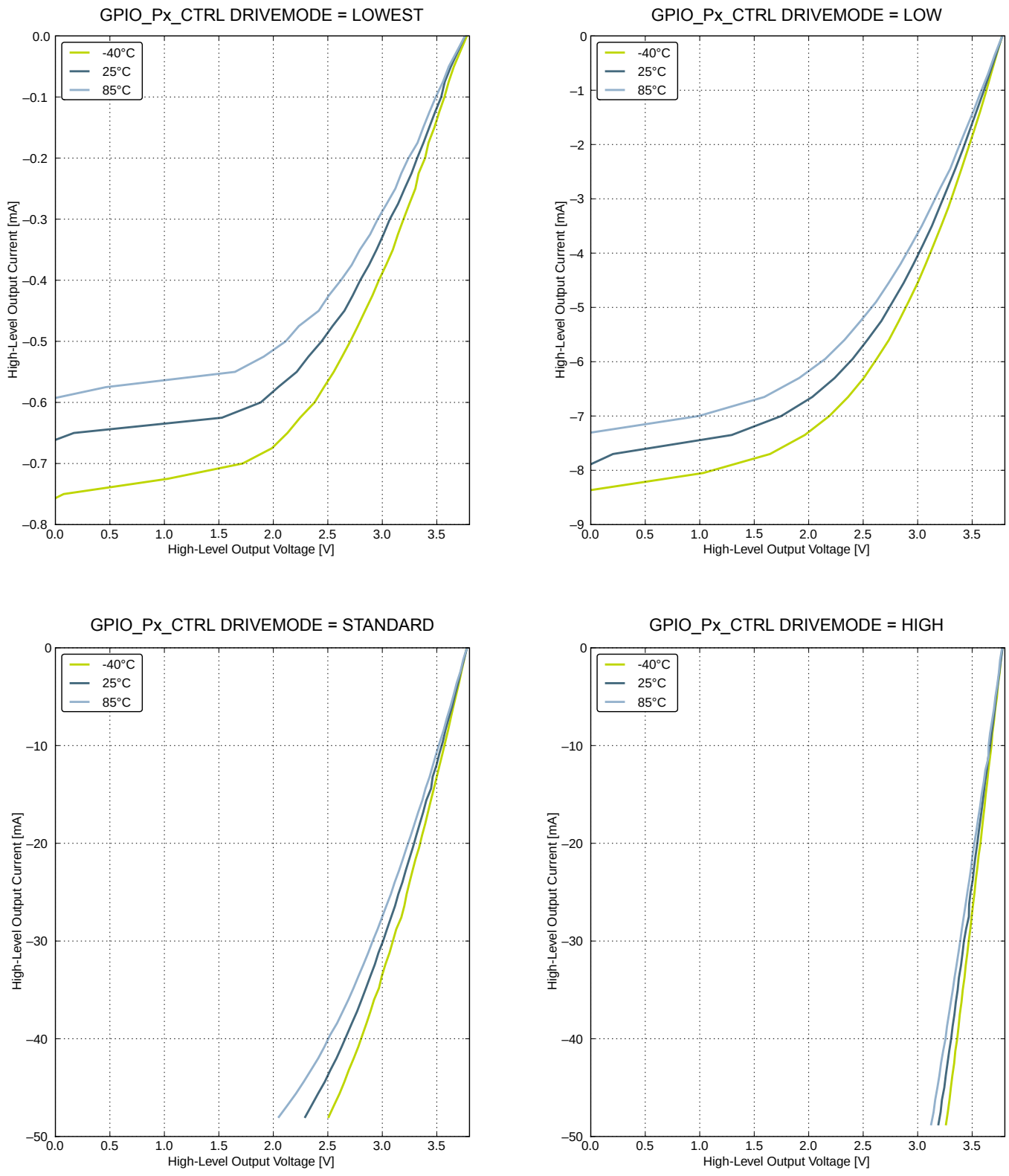

Figure 4.15. Typical High-Level Output Current, 3.8 V Supply Voltage

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 12 bit, single ended, internal 1.25 V reference	—	64	—	dBc
		1 MSamples/s, 12 bit, single ended, internal 2.5 V reference	—	76	—	dBc
		1 MSamples/s, 12 bit, single ended, VDD reference	—	73	—	dBc
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference	—	66	—	dBc
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference	—	77	—	dBc
		1 MSamples/s, 12 bit, differential, VDD reference	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, 2xVDD reference	—	75	—	dBc
		1 MSamples/s, 12 bit, differential, 5 V reference	—	69	—	dBc
		200 kSamples/s, 12 bit, single ended, internal 1.25 V reference	—	75	—	dBc
		200 kSamples/s, 12 bit, single ended, internal 2.5 V reference	—	75	—	dBc
		200 kSamples/s, 12 bit, single ended, VDD reference	—	76	—	dBc
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, 5 V reference	—	78	—	dBc
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	200 kSamples/s, 12 bit, differential, VDD reference	68	79	—	dBc
		200 kSamples/s, 12 bit, differential, 2xVDD reference	—	79	—	dBc
Offset voltage	$V_{ADCOFFSET}$	After calibration, single ended	-3.5	0.3	3	mV
		After calibration, differential	—	0.3	—	mV
Thermometer output gradient	$TGRAD_{ADCTH}$		—	-1.92	—	mV/°C
			—	-6.3	—	ADC Codes/°C
Differential non-linearity (DNL)	DNL_{ADC}		-1	±0.7	4	LSB
Integral non-linearity (INL), End point method	INL_{ADC}		—	±1.2	±3	LSB
Missing codes	MC_{ADC}		11.999[1]	12	—	bits
Gain error drift	$GAIN_{ED}$	1.25 V reference	—	0.01[2]	0.033[3]	%/°C
		2.5 V reference	—	0.01[2]	0.03[3]	%/°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Gain Bandwidth Product	GBW_{OPAMP}	(OPA0)BIASPROG=0x0,(OPA0)HALFBIAS=0x1, DC bias = 0.3 V	—	0.393[1]	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALFBIAS=0x1, DC bias = 1 V	—	0.487[1]	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALFBIAS=0x1, DC bias = 2 V	—	0.392[1]	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALFBIAS=0x1, DC bias = 2.7 V	—	0.318[1]	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALFBIAS=0x1, DC bias = 0.3 V	—	1.595[1]	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALFBIAS=0x1, DC bias = 1 V	—	2.661[1]	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALFBIAS=0x1, DC bias = 2 V	—	2.566[1]	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALFBIAS=0x1, DC bias = 2.7 V	—	1.787[1]	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALFBIAS=0x1, DC bias = 0.3 V	—	0.460[1]	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALFBIAS=0x1, DC bias = 1 V	—	0.447[1]	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALFBIAS=0x1, DC bias = 2 V	—	0.372[1]	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALFBIAS=0x1, DC bias = 2.7 V	—	0.295[1]	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALFBIAS=0x1, DC bias = 0.3 V	—	1.890[1]	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALFBIAS=0x1, DC bias = 1 V	—	2.849[1]	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALFBIAS=0x1, DC bias = 2 V	—	2.561[1]	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALFBIAS=0x1, DC bias = 2.7 V	—	1.705[1]	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALFBIAS=0x1, DC bias = 0.3 V	—	0.339[1]	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALFBIAS=0x1, DC bias = 1 V	—	0.432[1]	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALFBIAS=0x1, DC bias = 2 V	—	0.347[1]	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALFBIAS=0x1, DC bias = 2.7 V	—	0.286[1]	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALFBIAS=0x1, DC bias = 0.3 V	—	1.271[1]	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALFBIAS=0x1, DC bias = 1 V	—	1.429[1]	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALFBIAS=0x1, DC bias = 2 V	—	1.283[1]	—	MHz

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. Measured with 70 pF load capacitance, 25 ºC, and 3 V, using a 100 mV p-p amplitude on the input signal.
2. Simulated with 70 pF load capacitance, 25 ºC, and 3 V, using a 1 mV p-p amplitude on the input signal.

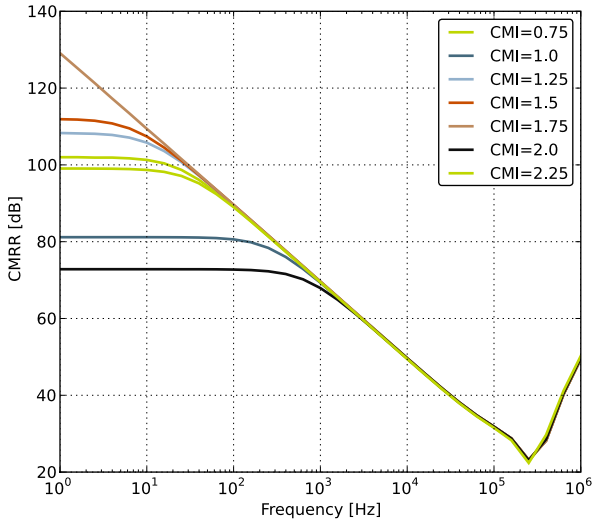

Figure 4.31. OPAMP Common Mode Rejection Ratio

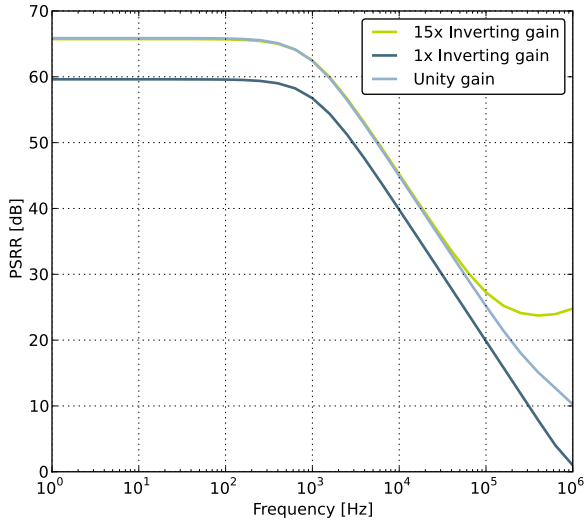

Figure 4.32. OPAMP Positive Power Supply Rejection Ratio

4.14 Voltage Comparator (VCMP)

Table 4.18. VCMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{VCMPIN}		—	V_{DD}	—	V
VCMP Common Mode voltage range	V_{VCMPCM}		—	V_{DD}	—	V
Active current	I_{VCMP}	BIASPROG=0b0000 and HALFBIAS=1 in VCMPn_CTRL register	—	0.3[1]	0.6[1]	µA
		BIASPROG=0b1111 and HALFBIAS=0 in VCMPn_CTRL register. LPREF=0.	—	22[1]	35[1]	µA
Startup time reference generator	$t_{VCMPREF}$	NORMAL	—	10	—	µs
Offset voltage	$V_{VCMPOFFSET}$	Single ended	—	10	—	mV
		Differential	—	10	—	mV
Negative hysteresis	$V_{VCMPHYST\_N}$	BIASPROG=0b0000, HALFBIAS=1, LPREF=1	-46.6	-15.6	11.4	mV
Positive hysteresis	$V_{VCMPHYST\_P}$	BIASPROG=0b0000, HALFBIAS=1, LPREF=1	-7.5	23.4	46.6	mV
Hysteresis delta	$V_{VCMPHYST\_DELTA}$	BIASPROG=0b0000, HALFBIAS=1, LPREF=1	4.2	35.2	70.0	mV
Startup time	$t_{VCMPSTART}$		—	—	10	µs
Negative response time	$t_{RESPONSE\_N}$	BIASPROG=0b0000, HALFBIAS=1, LPREF=1, HYSTSEL=0	—	372.3	—	µs
Positive response time	$t_{RESPONSE\_P}$	BIASPROG=0b0000, HALFBIAS=1, LPREF=1, HYSTSEL=0	—	865.7	—	µs

Note:
1. Includes required contribution from the voltage reference.

The V_{DD} trigger level can be configured by setting the TRIGLEVEL field of the VCMP_CTRL register in accordance with the following equation:

$$V_{DD\ Trigger\ Level} = 1.667V + 0.034 \times TRIGLEVEL$$

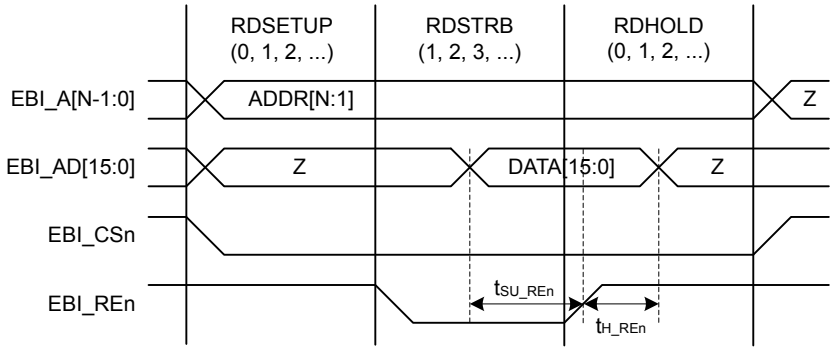

Figure 4.40. EBI Read Enable Related Timing Requirements

Table 4.22. EBI Read Enable Related Timing Requirements

Parameter	Symbol	Min	Typ	Max	Unit
Setup time, from EBI_AD valid to trailing EBI_REn edge	t_{SU_REn} [1 2 3 4]	37	—	—	ns
Hold time, from trailing EBI_REn edge to EBI_AD invalid	t_{H_REn} [1 2 3 4]	-1	—	—	ns

Note:

1. Applies for all addressing modes (figure only shows D16A8).
2. Applies for both EBI_REn and EBI_NANDREn (figure only shows EBI_REn)
3. Applies for all polarities (figure only shows active low signals)
4. Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

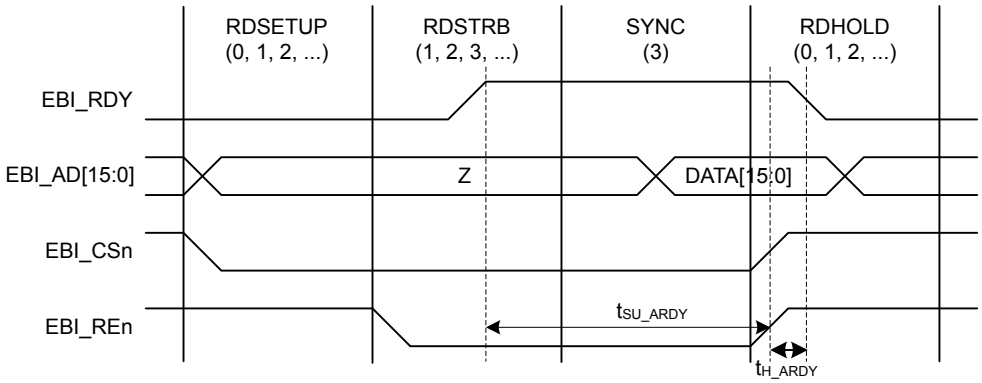

Figure 4.41. EBI Ready/Wait Related Timing Requirements

Table 4.23. EBI Ready/Wait Related Timing Requirements

Parameter	Symbol	Min	Typ	Max	Unit
Setup time, from EBI_ARDY valid to trailing EBI_REn, EBI_WEn edge	t_{SU_ARDY} [1 2 3 4]	37 + (3 × $t_{HFCORECLK}$)	—	—	ns
Hold time, from trailing EBI_REn, EBI_WEn edge to EBI_ARDY invalid	t_{H_ARDY} [1 2 3 4]	-1	—	—	ns

Note:

1. Applies for all addressing modes (figure only shows D16A8.)
2. Applies for EBI_REn, EBI_WEn (figure only shows EBI_REn)
3. Applies for all polarities (figure only shows active low signals)
4. Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US2_TX	PC2	PB3						USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.4.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32LG290 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.12. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	—	—	—	—	—	—	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

5.4.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG290 is shown in the following figure.

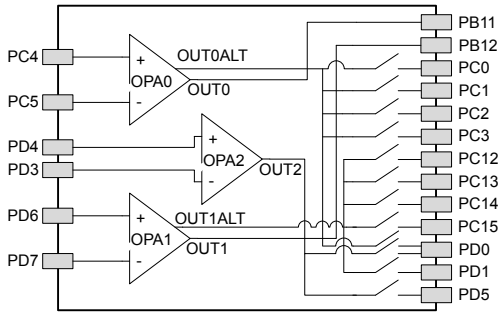

Figure 5.8. Opamp Pinout

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
CMU_CLK0	PA2		PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							
DAC0_OUT1ALT / OPAMP_OUT1ALT					PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
ETM_TCLK	PD7		PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6		PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5		PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
U0_RX	PF7	PE1	PA4					UART0 Receive input.
U0_TX	PF6	PE0	PA3					UART0 Transmit output. Also used as receive input in half duplex communication.
U1_RX		PF11	PB10	PE3				UART1 Receive input.
U1_TX		PF10	PB9	PE2				UART1 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		PB14	PB14		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10	PE12	PB8	PC1		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11	PE13	PB7	PC0		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX	PC1	PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0	PD7					USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.
USB_DP	PF11							USB D+ pin.
USB_ID	PF12							USB ID pin. Used in OTG mode.
USB_VBUS	USB_VBUS							USB 5 V VBUS input.
USB_VBUSEN	PF5							USB 5 V VBUS enable.

QFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PA2	LCD_SEG15	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3	LCD_SEG16	TIM0_CDTI0 #0		LES_ALTEX2 #0 ETM_TD1 #3
5	PA4	LCD_SEG17	TIM0_CDTI1 #0		LES_ALTEX3 #0 ETM_TD2 #3
6	PA5	LCD_SEG18	TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PB3	LCD_SEG20/ LCD_COM4	PCNT1_S0IN #1	US2_TX #1	
10	PB4	LCD_SEG21/ LCD_COM5	PCNT1_S1IN #1	US2_RX #1	
11	PB5	LCD_SEG22/ LCD_COM6		US2_CLK #1	
12	PB6	LCD_SEG23/ LCD_COM7		US2_CS #1	
13	PC4	ACMP0_CH4 OPAMP_P0	TIM0_CDTI2 #4 LE- TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
14	PC5	ACMP0_CH5 OPAMP_N0	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
15	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
16	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
17	PA12	LCD_BCAP_P	TIM2_CC0 #1		
18	PA13	LCD_BCAP_N	TIM2_CC1 #1		
19	PA14	LCD_BEXT	TIM2_CC2 #1		
20	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0 / OPAMP_OUT0	TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
25	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	PC1	PF2		Timer 0 Capture Compare input / output channel 2.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_A06	PC7	PC7	PC7					External Bus Interface (EBI) address output pin 06.
EBI_A07	PE0	PE0	PE0					External Bus Interface (EBI) address output pin 07.
EBI_A08	PE1	PE1	PE1					External Bus Interface (EBI) address output pin 08.
EBI_A09	PE2	PC9	PC9					External Bus Interface (EBI) address output pin 09.
EBI_A10	PE3	PC10	PC10					External Bus Interface (EBI) address output pin 10.
EBI_A11	PE4	PE4	PE4					External Bus Interface (EBI) address output pin 11.
EBI_A12	PE5	PE5	PE5					External Bus Interface (EBI) address output pin 12.
EBI_A13	PE6	PE6	PE6					External Bus Interface (EBI) address output pin 13.
EBI_A14	PE7	PE7	PE7					External Bus Interface (EBI) address output pin 14.
EBI_A15	PC8	PC8	PC8					External Bus Interface (EBI) address output pin 15.
EBI_A16	PB0	PB0	PB0					External Bus Interface (EBI) address output pin 16.
EBI_A17	PB1	PB1	PB1					External Bus Interface (EBI) address output pin 17.
EBI_A18	PB2	PB2	PB2					External Bus Interface (EBI) address output pin 18.
EBI_A19	PB3	PB3	PB3					External Bus Interface (EBI) address output pin 19.
EBI_A20	PB4	PB4	PB4					External Bus Interface (EBI) address output pin 20.
EBI_A21	PB5	PB5	PB5					External Bus Interface (EBI) address output pin 21.
EBI_A22	PB6	PB6	PB6					External Bus Interface (EBI) address output pin 22.
EBI_A23	PC0	PC0	PC0					External Bus Interface (EBI) address output pin 23.
EBI_A24	PC1	PC1	PC1					External Bus Interface (EBI) address output pin 24.
EBI_A25	PC2	PC2	PC2					External Bus Interface (EBI) address output pin 25.
EBI_A26	PC4	PC4	PC4					External Bus Interface (EBI) address output pin 26.
EBI_A27	PD2	PD2	PD2					External Bus Interface (EBI) address output pin 27.
EBI_AD00	PE8	PE8	PE8					External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9	PE9	PE9					External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10	PE10	PE10					External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11	PE11	PE11					External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12	PE12	PE12					External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13	PE13	PE13					External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	PE14	PE14	PE14					External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.

5.19.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG942 is shown in the following figure.

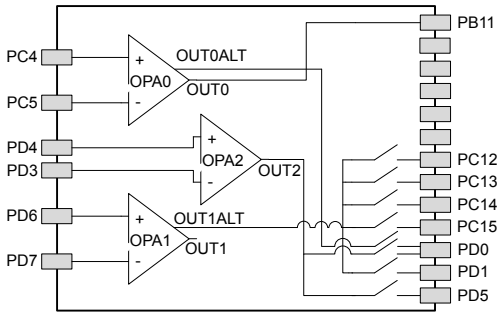

Figure 5.38. Opamp Pinout

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
L8	PB13	HFXTAL_P			US0_CLK #4/5 LEU0_TX #1	
L9	PB14	HFXTAL_N			US0_CS #4/5 LEU0_RX #1	
L10	AVDD_0	Analog power supply 0.				
L11	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	

14.2 Revision 1.31

December 16th, 2015

Removed Environmental section from General Operating Conditions.

Added max current consumption numbers for energy modes.

For devices with an ADC, added clarification on conditions for INL_{ADC} and DNL_{ADC} parameters.

For devices with an EBI, updated EBI ready/wait figure.

Updated memory map.

Removed DC_{HFRCO} and $DC_{AUXHFRCO}$ parameters.

For CSP81 package, updated typical and added min/max values for f_{HFRCO} and $f_{AUXHFRCO}$.

For devices in CSP81 package with a DAC, updated OPAMP table.

Fixed typos

Added OPAMP, ADC, and ACMP Input Bias Current and Input Offset Current specifications.

Added lower limit for GPIO Input Leakage Current and updated the upper limit for this specification.

Removed the "by simulation and/or technology characterization" phrase from the Electrical Characteristics Test Conditions section.

14.3 Revision 1.30

June 13th, 2014

This revision applies the following devices:

- EFM32LG230
- EFM32LG232
- EFM32LG280
- EFM32LG290
- EFM32LG295
- EFM32LG330
- EFM32LG332
- EFM32LG380
- EFM32LG390
- EFM32LG395
- EFM32LG840
- EFM32LG842
- EFM32LG880
- EFM32LG890
- EFM32LG895
- EFM32LG940
- EFM32LG942
- EFM32LG980
- EFM32LG990
- EFM32LG995

Removed "Preliminary" markings.

Updated electrical characteristics and updated/added plots.

Updated orderable part numbers.

Added AUXHFRCO to block diagram and electrical characteristics.

For devices with EBI, added EBI timing chapter.